



BSI Standards Publication

Device embedding assembly technology

Part 2-8: Guidelines — Warpage control of active device embedded substrate

National foreword

This Published Document is the UK implementation of IEC TR 62878-2-8:2021.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Published by BSI Standards Limited 2021

ISBN 978 0 539 13658 6

ICS 31.180; 31.190

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This Published Document was published under the authority of the Standards Policy and Strategy Committee on 31 August 2021.

Amendments/corrigenda issued since publication

Date	Text affected
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